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Nota di contenuto	Chapter 1. Introduction -- Chapter 2. Twisted-Tape Insert -- Chapter 3. Displaced Enhancement Devices and Wire Coil Inserts -- Chapter 4. Swirl Generators, Extended Surface Insert and Tangential Injection Devices -- Chapter 5. Numerical Simulation of Integral Roughness, Laminar Flow in Tubes with Roughness -- Chapter 6. 2D Roughness, 3D roughness and Roughness Applications -- Chapter 7. Compound Techniques -- Chapter 8. Conclusions.
Sommario/riassunto	This Brief describes heat transfer and pressure drop in heat transfer enhancement by insert devices and integral roughness. The authors deal with twisted-tape insert laminar and turbulent flow in tubes and annuli in smooth tubes and rough tubes, segmented twisted-tape inserts, displaced enhancement devices, wire coil inserts, extended

surface inserts and tangential injection devices. The articles also address transverse and helical integral rib roughness, corrugated tube roughness, 3D and 2D roughness, rod bundles, outside roughness for cross flow, non-circular channels, Reynolds analogy and similarity law, numerical simulation and predictive models. The book is ideal for professionals and researchers working with thermal management in devices. .
